

ABSTRACT

A bonding system includes a plurality of bonders configured to separate dies from carriers to bond the separated dies to target substrates; a transfer apparatus configured to transfer the carriers and the target substrates to the plurality of bonders; and control circuitry configured to control the plurality of bonders and the transfer apparatus. The control circuitry is further configured to perform control to cause, during a desired period, the plurality of the bonders to repeatedly bond, to the target substrates, the only one type of the dies set for each of the plurality of the bonders while replacing the target substrates; and control to cause, during the desired period, the transfer apparatus to sequentially transfer each of the target substrates to the plurality of the bonders that are configured to bond different types of the dies to the target substrates.

FIG. 15